



LAYER DETAIL  
NOT TO SCALE

DRILL TABLE		
×	0.012"	10
○	0.016"	915
+	0.039"	34
×	0.039"	2 NP
□	0.040"	75
◇	0.043"	6
⊗	0.070"	12
×	0.074"	6
○	0.126"	4 NP

## NOTES:

- MATERIAL TO BE NEMA GRADE FR-4 .063 THICK, 1 OZ. COPPER CLAD. INNER LAYERS TO BE 1/2 OZ. COPPER.
- DIELECTRIC CONSTANT OF BOARD MATERIAL SHALL BE 4.650 +/- .350.
- FINISHED DETAIL BOARD THICKNESS SHALL BE .055 TO .070.  
BOARD THICKNESS TO BE MEASURED OVER SILKSCREEN AND SOLDERMASK ALONG THE BOARD EDGES.
- SOLDERMASK ARTWORK IS A PAD MASTER ARTWORK, SOLDERMASK BOTH SIDES OF BOARD.  
BOARD VENDOR MAY MICRO MODIFY THE SOLDER MASK PADS TO MEET THE REQUIREMENTS OF THE EMS PROVIDER.
- SILKSCREEN ON SOLDER PLATED PAD IS NOT PERMISSIBLE.  
VENDOR IS TO PHOTOGRAPHICALLY ALTER ARTWORK TO INSURE THERE IS NO SILKSCREEN ON COMP. PADS.
- DETAIL BOARD FINISH SHALL BE HASL.
- BOARD VENDOR TO REPLACE XXXX ON BOTTOM SIDE OF BOARD WITH LOT CODE AND LOGO.
- VIEWED FROM COMPONENT SIDE OF BOARD.
- IMPEDANCE REQUIREMENT:  
TOP: DIFFERENTIAL  
0.008" LINE, 0.007" SPACE, 90 OHMS +/-10%
- BOARD VENDOR MAY MODIFY DIELECTRIC THICKNESS SPECIFIED IN LAYER DETAIL TO MEET IMPEDANCE REQUIREMENT.

